

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	9025687
<b>Application Number:</b>	10755042
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	8665
<b>Title of Invention:</b>	Integrated chip package structure using silicon substrate and method of manufacturing the same
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin
<b>Customer Number:</b>	89518
<b>Filer:</b>	Dennis Alan Duchene/ShirLynn Mata
<b>Filer Authorized By:</b>	Dennis Alan Duchene
<b>Attorney Docket Number:</b>	085027-0104
<b>Receipt Date:</b>	13-DEC-2010
<b>Filing Date:</b>	09-JAN-2004
<b>Time Stamp:</b>	20:05:22
<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$ 180
RAM confirmation Number	6878
Deposit Account	502624
Authorized User	

The Director of the USPTO is hereby authorized to charge indicated fees and credit any overpayment as follows:

Charge any Additional Fees required under 37 C.F.R. Section 1.21 (Miscellaneous fees and charges)

File Listing:					
Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Transmittal Letter	InformationDisclosureState mentTransmittal1-085027-0104. pdf	71355	no	3
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Information:					
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**New Applications Under 35 U.S.C. 111**

**If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.**

**National Stage of an International Application under 35 U.S.C. 371**

**If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.**

**New International Application Filed with the USPTO as a Receiving Office**

**If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.**